

STRUCTURE
TYPE
PRODUCT SERIES
FEATURES

Silicon Monolithic Integrated Circuit
1ch DC/DC converter IC
BD95503MUV

- Built in 1ch H³Reg DC/DC converter controller
- Adjustable output voltage setting (0.75V~5.5V)

○ Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limit	Unit
Input Voltage	VIN, VINS	24 * ¹⁺²	V
BOOT Voltage	BOOT	30 * ¹⁺²	V
BOOT-SW Voltage	BOOT-SW	7 * ¹⁺²	V
Output Voltage	VOUT	7 * ¹⁺²	V
Output Feedback Voltage	FB	VREG	V
VREG Voltage	VREG	7 * ¹⁺²	V
Current Limit Setting Voltage	ILIM	VREG	V
Logic Input Voltage	EN	24 * ¹⁺²	V
Output Current (Average)	Isw	3 * ¹	A
Power Dissipation 1	Pd1	0.34 * ³	W
Power Dissipation 2	Pd2	0.70 * ⁴	W
Power Dissipation 3	Pd3	1.21 * ⁵	W
Power Dissipation 4	Pd4	3.56 * ⁶	W
Operating Temperature Range	Topr	-20~+100	°C
Storage Temperature Range	Tstg	-55~+150	°C
Maximum Junction Temperature	Tjmax	+150	°C

*1 Not to exceed Pd.

*2 Instantaneous surge voltage, back electromotive force and voltage under less than 10% duty cycle.

*3 Reduced by 2.7mW/°C for each increase in Ta of 1°C over 25°C (when don't mounted on a heat radiation board)

*4 Reduced by 5.6mW/°C for increase in Ta of 1°C over 25°C. (when mounted on a board 74.2mm × 74.2mm × 1.6mm Glass-epoxy PCB, copper foil area : 10.29mm²)

*5 Reduced by 9.7mW/°C for increase in Ta of 1°C over 25°C. (when mounted on a board 74.2mm × 74.2mm × 1.6mm Glass-epoxy PCB, copper foil area: 10.29mm², 2-3layer: 5505mm²)

*6 Reduced by 28.5mW/°C for increase in Ta of 1°C over 25°C. (when mounted on a board 74.2mm × 74.2mm × 1.6mm Glass-epoxy PCB, copper foil area: 5505mm²)

○ Operating Conditions (Ta=25°C)

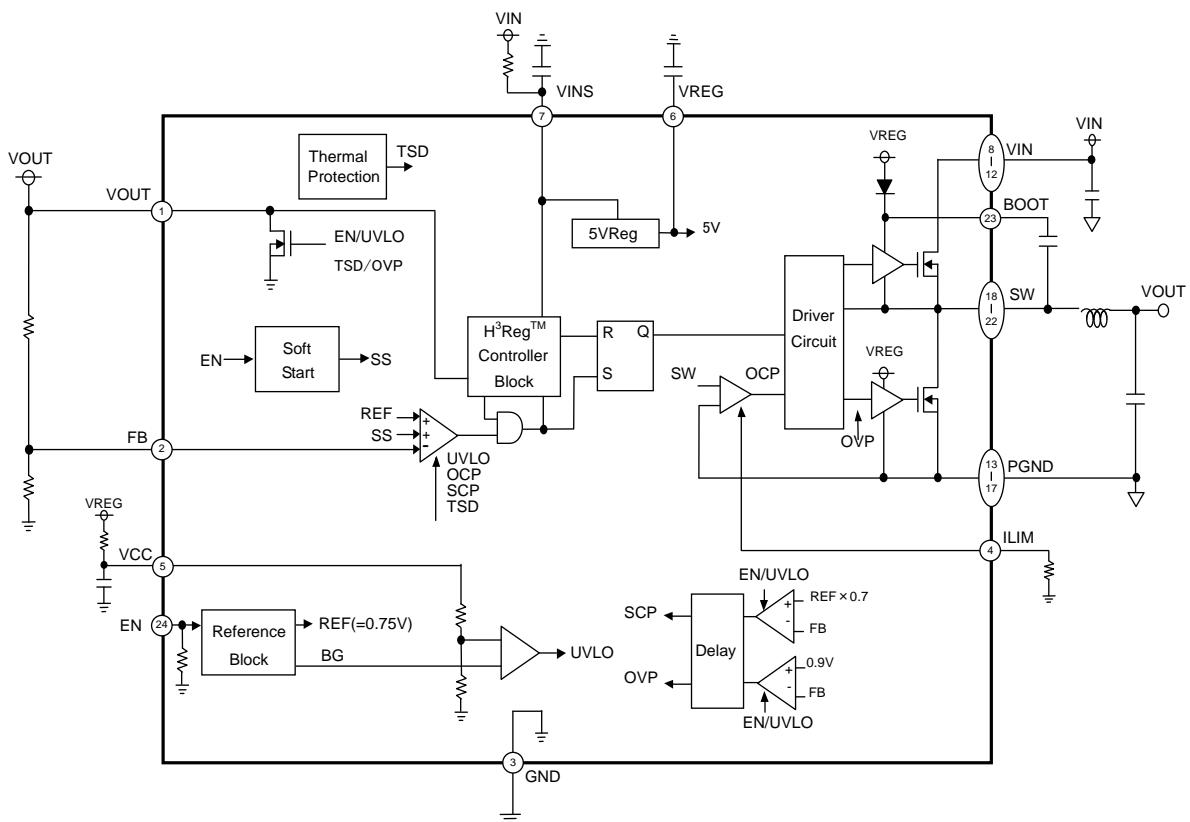
Parameter	Symbol	MIN.	MAX.	Unit
Input Voltage	VIN, VINS	7.5	20	V
BOOT Voltage	BOOT	4.5	25	V
SW Voltage	SW	-0.7	20	V
BOOT-SW Voltage	BOOT-SW	4.5	5.5	V
Logic Input Voltage	EN	0	20	V
Output Voltage	VOUT	0.75	5.5	V
MIN ON TIME	tonmin	-	100	ns

● This product is not designed to be used in a radioactive environment.

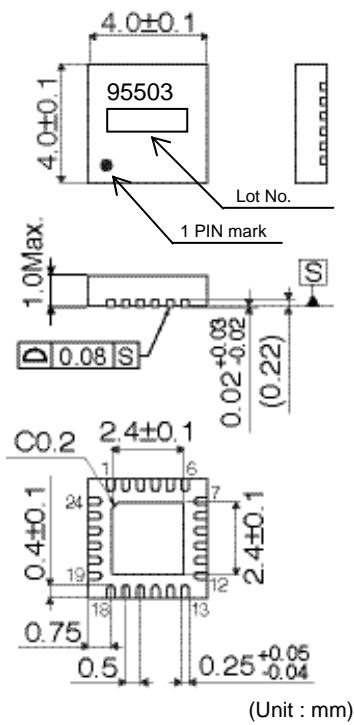
○Electrical Characteristics (Unless otherwise noted, Ta=25°C VCC=5V, VIN=VINS=12V, VEN=3V, VOUT=1.8V)

Parameter	Symbol	Standard Value			Unit	Conditions
		MIN.	TYP.	MAX.		
[Whole Device]						
VIN Bias current	I _{IN}	-	1.0	2.0	mA	VCC=VREG
VIN Standby current	I _{IN_stb}	-	0	10	μA	V _{EN} =0V
EN Low Voltage	V _{EN_low}	GND	-	0.3	V	
EN High Voltage	V _{EN_high}	2.2	-	20	V	
EN Pull-down resistance	R _{EN}	30	50	70	kΩ	
[5VLinear Regulator]						
VREG Standby Voltage	V _{REG_stb}	-	-	0.1	V	V _{EN} =0V
VREG Output Voltage	V _{REG}	4.9	5.1	5.3	V	VIN=VINS=7.5V to 20V I _{reg} =10mA
[Under Voltage Lock Out]						
VREG threshold Voltage	V _{REG_UVLO}	3.75	4.20	4.65	V	V _{REG} :Sweep up
VREG hysteresis Voltage	dV _{REG_UVLO}	100	160	220	mV	V _{REG} :Sweep down
[Over Voltage Protection]						
FB threshold Voltage	F _{B_OVP}	0.8	0.9	1.0	V	
[H³RegTM Control]						
ON Time	t _{on}	200	300	400	ns	
MIN OFF Time	T _{offmin}	300	500	-	ns	
[FET Driver]						
High side ON resistance	R _{HGon}	-	0.270	0.540	Ω	
Low side ON resistance	R _{LGon}	-	0.135	0.270	Ω	
[Current Control]						
Current Limit threshold Voltage	V _{ilim}	440	470	500	mV	R _{ILIM} =47kΩ
[Output Voltage Sense]						
FB threshold Voltage	F _B	0.738	0.750	0.762	V	
FB Input current	I _{FB}	-1	-	1	μA	
VOUT discharge current	I _{VOUT}	5	10	-	mA	VOUT=1V, V _{EN} =0V
[SCP]						
Threshold Voltage	V _{thscp}	REF × 0.6	REF × 0.7	REF × 0.8	V	

○ Block Diagram



○ Physical Dimension



○ Pin number • Pin name

PIN No.	PIN name
1	VOUT
2	FB
3	GND
4	ILIM
5	VCC
6	VREG
7	VINS
8-12	VIN
13-17	PGND
18-22	SW
23	BOOT
24	EN
Reverse	FIN

○ NOTE FOR USE

1. Absolute maximum ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.

2. Supply line

Since the motor's reverse electromotive force gives rise to the return of regenerative current, measures should be taken to establish a channel for the current, such as adding a capacitor between the power supply and GND. In determining the approach to take, make sure that no problems will be posed by the various characteristics involved, such as capacitance loss at low temperatures with an electrolytic capacitor.

3. GND voltage

The potential of GND, PGND pin must be minimum potential in all operating conditions.

4. Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation (P_d) in actual operating conditions.

5. Inter-pin shorts and mounting errors

Use caution when positioning the IC for mounting on printed circuit boards. The IC may be damaged if there is any connection error or if pins are shorted together.

6. Actions in strong electromagnetic field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

7. ASO

When using the IC, set the output transistor so that it does not exceed absolute maximum ratings or ASO.

8. Testing on application boards

When testing the IC on an application board, connecting a capacitor to a pin with low impedance subjects the IC to stress. Always discharge capacitors after each process or step. Always turn the IC's power supply off before connecting it to or removing it from a jig or fixture during the inspection process. Ground the IC during assembly steps as an antistatic measure. Use similar precaution when transporting or storing the IC.

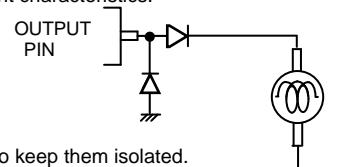
9. Electrical characteristics

The electrical characteristics in the Specifications may vary depending on ambient temperature, power supply voltage, circuit(s) externally applied, and/or other conditions. It is therefore requested to carefully check them including transient characteristics.

10. Not of a radiation-resistant design.

11. In the event that load containing a large inductance component

is connected to the output terminal, and generation of back-EMF at the start-up and when output is turned OFF is assumed, it is requested to insert a protection diode.



12. Regarding input pin of the IC

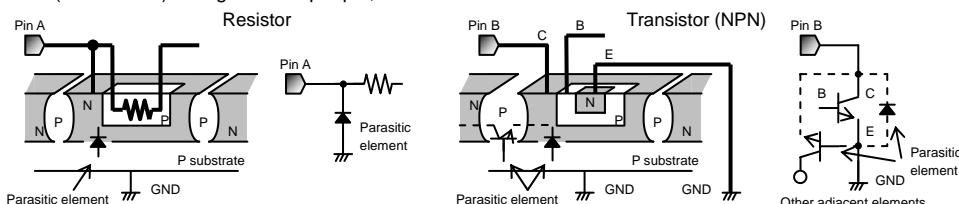
This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated.

P-N junctions are formed at the intersection of these P layers with the N layers of other elements, creating a parasitic diode or transistor. For example, the relation between each potential is as follows:

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode.

When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes can occur inevitable in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Accordingly, methods by which parasitic diodes operate, such as applying a voltage that is lower than the GND (P substrate) voltage to an input pin, should not be used.



13. Ground Wiring Pattern

When using both small signal and large current GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the ground potential of application so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring pattern of any external components, either.

14. Operating ranges

If it is within the operating ranges, certain circuit functions and operations are warranted in the working ambient temperature range. With respect to characteristic values, it is unable to warrant standard values of electric characteristics but there are no sudden variations in characteristic values within these ranges.

15. Thermal shutdown circuit

This IC is provided with a built-in thermal shutdown (TSD) circuit, which is activated when the chip temperature reaches the threshold value listed below. When TSD is on, the device goes to high impedance mode. Note that the TSD circuit is provided for the exclusive purpose shutting down the IC in the presence of extreme heat, and is not designed to protect the IC per se or guarantee performance when or after extreme heat conditions occur. Therefore, do not operate the IC with the expectation of continued use or subsequent operation once the TSD is activated.

TSD ON temperature [°C] (typ.)	Hysteresis temperature[°C] (typ.)
175	15

16. Output Voltage Resistor Setting

Output voltage is adjusted with resistor. Total 10kohm resistor is recommended so that the output voltage is not affected by the FB input current (Typ. 1uA).

17. Heat sink (FIN)

Since the heat sink (FIN) is connected with the Sub, short it to the GND.

Notes

No copying or reproduction of this document, in part or in whole, is permitted without the consent of ROHM Co.,Ltd.

The content specified herein is subject to change for improvement without notice.

The content specified herein is for the purpose of introducing ROHM's products (hereinafter "Products"). If you wish to use any such Product, please be sure to refer to the specifications, which can be obtained from ROHM upon request.

Examples of application circuits, circuit constants and any other information contained herein illustrate the standard usage and operations of the Products. The peripheral conditions must be taken into account when designing circuits for mass production.

Great care was taken in ensuring the accuracy of the information specified in this document. However, should you incur any damage arising from any inaccuracy or misprint of such information, ROHM shall bear no responsibility for such damage.

The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM and other parties. ROHM shall bear no responsibility whatsoever for any dispute arising from the use of such technical information.

The Products specified in this document are intended to be used with general-use electronic equipment or devices (such as audio visual equipment, office-automation equipment, communication devices, electronic appliances and amusement devices).

The Products specified in this document are not designed to be radiation tolerant.

While ROHM always makes efforts to enhance the quality and reliability of its Products, a Product may fail or malfunction for a variety of reasons.

Please be sure to implement in your equipment using the Products safety measures to guard against the possibility of physical injury, fire or any other damage caused in the event of the failure of any Product, such as derating, redundancy, fire control and fail-safe designs. ROHM shall bear no responsibility whatsoever for your use of any Product outside of the prescribed scope or not in accordance with the instruction manual.

The Products are not designed or manufactured to be used with any equipment, device or system which requires an extremely high level of reliability the failure or malfunction of which may result in a direct threat to human life or create a risk of human injury (such as a medical instrument, transportation equipment, aerospace machinery, nuclear-reactor controller, fuel-controller or other safety device). ROHM shall bear no responsibility in any way for use of any of the Products for the above special purposes. If a Product is intended to be used for any such special purpose, please contact a ROHM sales representative before purchasing.

If you intend to export or ship overseas any Product or technology specified herein that may be controlled under the Foreign Exchange and the Foreign Trade Law, you will be required to obtain a license or permit under the Law.

Thank you for your accessing to ROHM product informations.
More detail product informations and catalogs are available, please contact us.

ROHM Customer Support System

<http://www.rohm.com/contact/>

